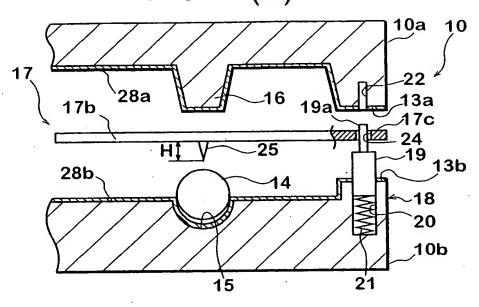
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FIG. 1 (A)



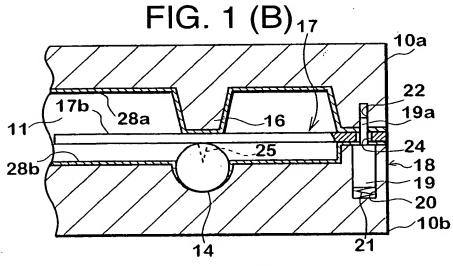
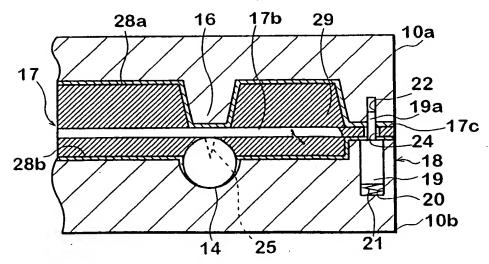


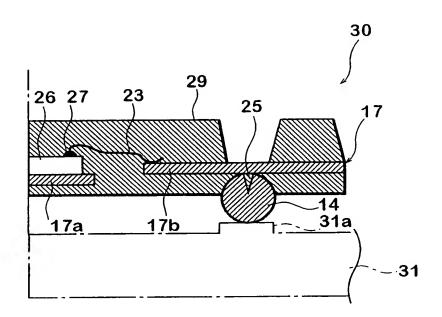
FIG. 1 (C)



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6 sheets of drawings FIGS.1A-7C
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FIG. 2

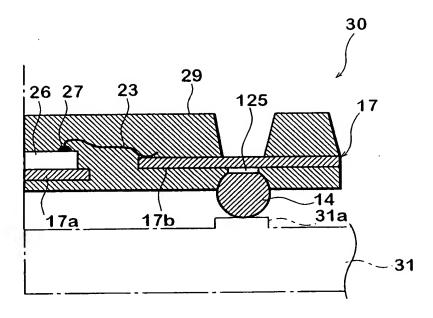
Attv\_Docket:\_OKI\_286\_



PACKAGE (1)

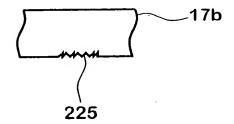
New Application: TERUI et al.
Title: SEMICONDUCTOR PACKAGE.....
d: December 20, 2001
heets of drawings FIGS.1A-7C
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Customer NO.: 23995
Attv\_Docket: OKI.286.

FIG. 4



PACKAGE (2)

FIG. 5



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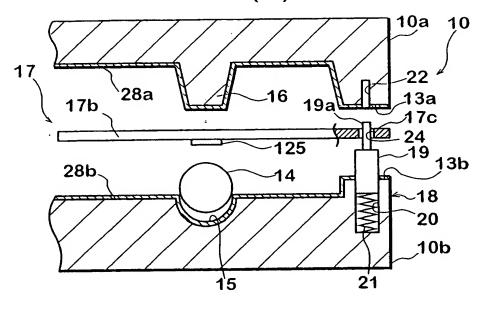
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## FIG. 3(A)



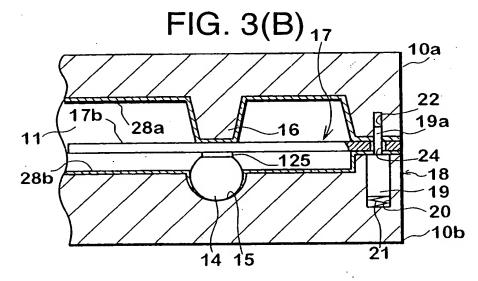


FIG. 3(C)

28a 16 17b 29

10a

22

19a

17c

28b

19a

19b

20

10b

125

14

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File Cember 20, 2001
6 sh of drawings FIGS.1A-7C
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## FIG. 6(A)

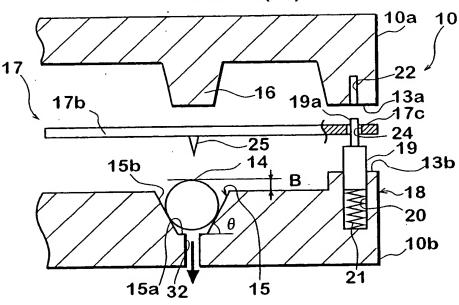


FIG. 6(B)

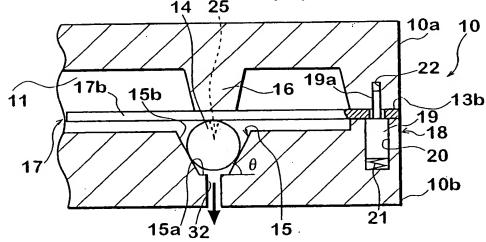
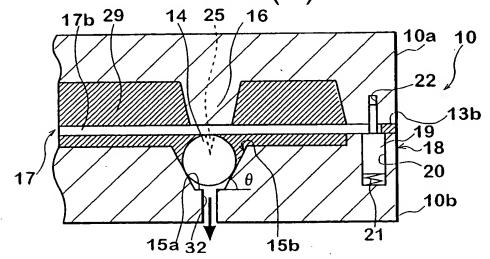


FIG. 6(C)



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Customer NO.: 23995



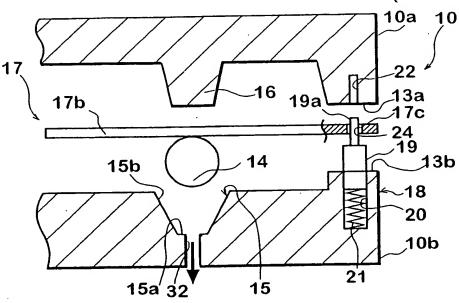


FIG. 7(B)

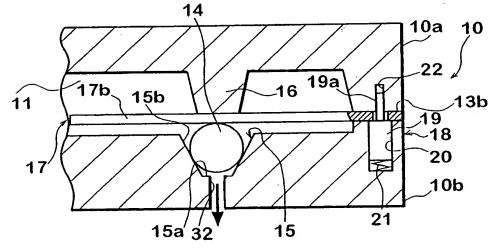


FIG. 7(C)

